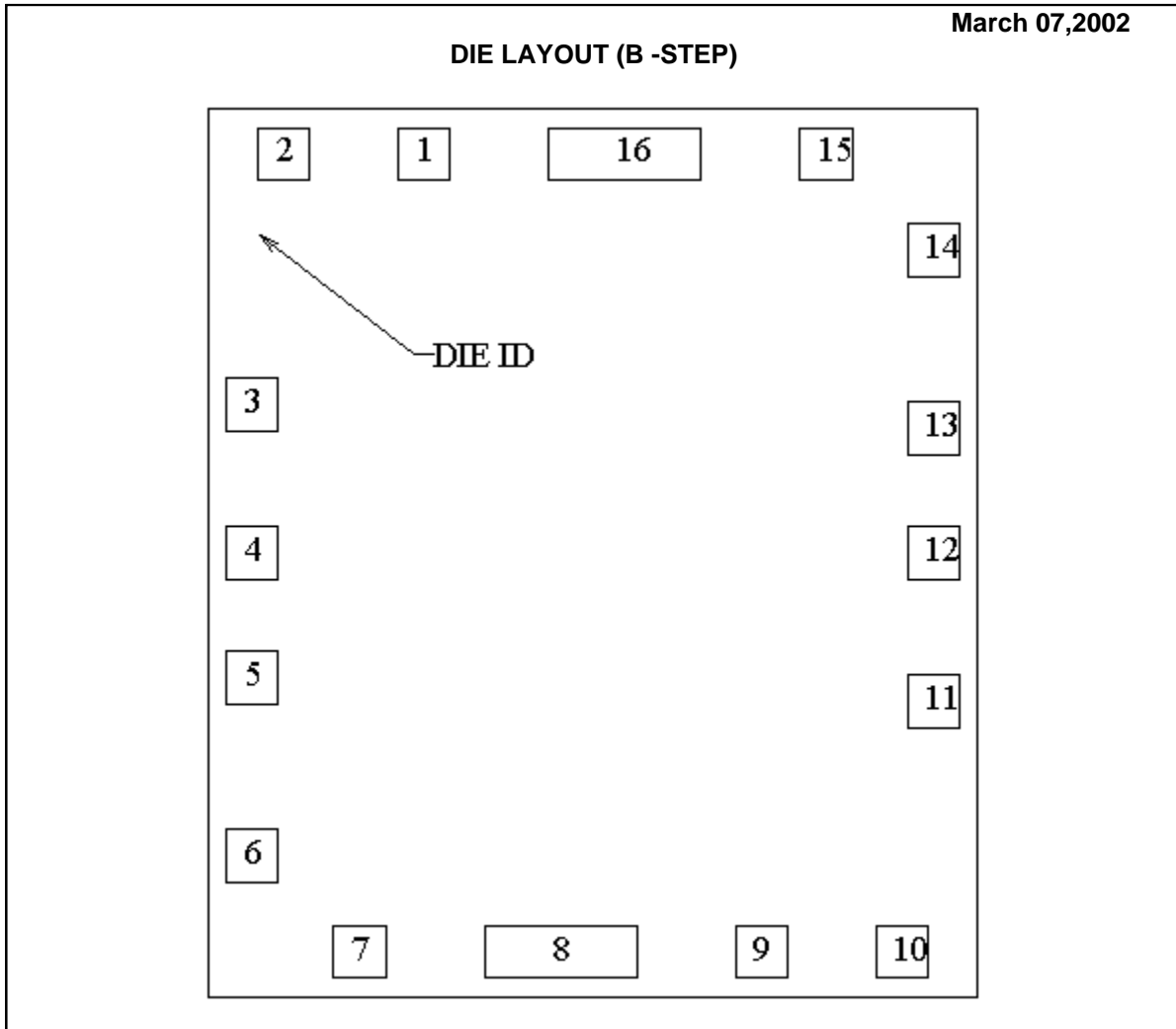


**DS26C31T MDC MWC**  
**CMOS QUAD TRI-STATE® DIFFERENTIAL LINE DRIVER**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	DS26C31B	Bond Pad Opening Size (min)	110µm x 110µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1626µm x 1880µm 64mils x 74mils	Back Side Connection	GND
Thickness	330µm Nominal		
Min Pitch	252µm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection						
SIGNAL	PAD#	X/Y CORRDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
INPUT A	1	-297	703	80	x	80
OUTPUT A+	2	-544	703	80	x	80
OUTPUT A-	3	-601	260	80	x	80
ENABLE	4	-601	0	80	x	80
OUTPUT B-	5	-601	-219	80	x	80
OUTPUT B+	6	-601	-536	80	x	80
INPUT B	7	-412	-703	80	x	80
GND	8	-57.5	-703	259	x	80
INPUT C	9	299	-703	80	x	80
OUTPUT C+	10	544	-703	80	x	80
OUTPUT C-	11	601	-261	80	x	80
/ENABLE	12	601	0	80	x	80
OUTPUT D-	13	601	218	80	x	80
OUTPUT D+	14	601	534	80	x	80
INPUT D	15	412	703	80	x	80
VCC	16	57.5	703	259	x	80

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